This document can handle board shapes up to 7.5m x 10m, although our panel renders top out at 7m x 10m.

To re-size the board shape, do the following:

1. Select Lines on H. Board Outline and delete (easy in single layer mode...shhhhh)
2. Draw a rectangle using lines (example will be for a 4 x 6 board
3. Enter Place Line mode (keyboard Q)
4. Keyboard J to jump to origin, hit enter
5. Keyboard J1 to jump to location, set x to 6000, hit enter twice
6. Keyboard J1 to jump to location, set x to 6000 and y to 4000, hit enter twice
7. Keyboard J1 to jump to origin, hit enter
8. Hit OVE to exit place line mode
9. Select Lines on H. Board Outline
10. Menu DesignBoard ShapeLine from Selected Objects (keyboard dd)

If you re-size the board, don’t forget to move the drill table strings on the Drill Drawing Layer...they should be just to the right of your board shape.
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